

Product / Process Change Notification



N° 2013-064-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of Bond Wire Material for Infineon Product TLE7241E in DSO300mil Package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **28. February 2014**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
- This PCN includes a **Product Discontinuation Notice** (JEDEC STANDARD "JESD48") on page 3/3

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

Product / Process Change Notification



N° 2013-064-A

SUBJECT OF CHANGE: 1.) Implementation of copper wire bonding for Infineon SPT5 product TLE7241E with exposed pad in DSO300mil package
2.) Revision of TLE7241E product data sheet

PRODUCTS AFFECTED:

TYPE	SP N°	OPN	Package
TLE7241E	SP000485116	TLE7241EXUMA1	PG-DSO-20-27

REASON OF CHANGE: Due to package portfolio management and alignment to overall DSO430mil bondwire strategy, Au bondwire is replaced by Cu bondwire.
For more information about Cu wire bonding at Infineon, please refer to addendum 3_cip13064

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
Package Name	PG-DSO-20-27	PG-DSO-20-67
Bond wire material	Au	Cu
Bond wire diameter	30µm	30µm
Order numbers	SP000485116	SP000877652
Data sheet revision	Rev. 1.1 (February 2009)	Rev. 1.11 (November 2013)

PRODUCT IDENTIFICATION:

- On Packing Level:
 - Different SP number
 - Package dash version changes from PG-DSO-20-27 to PG-DSO-20-67
- On Product Level:
Identification via lot number

TIME SCHEDULE:

■ Final qualification report:	Available	
■ First samples available:	Available	
■ Start of delivery:	July 31 st , 2014 or after alignment with customer	
■ Last order date of unchanged product:	July 31 st , 2014	See page 3/3
■ Last delivery date of unchanged product:	January 31 st , 2015	See page 3/3

ASSESSMENT:

No impact on parameters as defined in the product data sheet and reliability proven via technology and product qualification.

Changes in data sheet are restricted to the package name, no changes in physical parameters.

DOCUMENTATION:	2_cip13064	Final qualification report
	3_cip13064	Additional information on Cu wire bonding
	4_cip13064	Revised data sheet for TLE7241E

PRODUCT DISCONTINUATION

PD13064



referring to PCN N° 2013-064-A

■ Last order date of unchanged product:	2014-07-31
■ Last delivery date of unchanged product	2015-01-31

DISCONTINUED				NEW (REPLACEMENT)			
Device	SP N°	OPN	Package	Device	SP N°	OPN	Package
TLE7241E	SP000485116	TLE7241EXUMA1	PG-DSO-20-27	TLE7241E	SP000877652	TLE7241EXUMA2	PG-DSO-20-67

If you have any questions, please do not hesitate to contact your local Sales office.